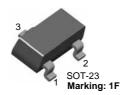


# MMBT5550 NPN General Purpose Amplifier

 This device is designed for general purpose high voltage amplifiers and gas discharge display drivers.



1. Base 2. Emitter 3. Collector

## Absolute Maximum Ratings \* $T_a = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	140	V
$V_{CBO}$	Collector-Base Voltage	160	V
$V_{EBO}$	Emitter-Base Voltage	6.0	V
I <sub>C</sub>	Collector current - Continuous	600	mA
T <sub>J</sub> , T <sub>stg</sub>	Junction and Storage Temperature	-55 ~ +150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

### Electrical Characteristics T<sub>a</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Charact	eristics		u.		
V <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage *	$I_C = 1.0 \text{mA}, I_B = 0$	140		V
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 100 \mu A, I_E = 0$	160		V
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 10 \text{mA}, I_C = 0$	6.0		V
I <sub>CBO</sub>	Collector Cutoff Current	V <sub>CB</sub> = 100V, I <sub>E</sub> = 0 V <sub>CB</sub> = 100V, I <sub>E</sub> = 0, T <sub>a</sub> = 100°C		100 100	nA μA
I <sub>EBO</sub>	Emitter Cutoff Current	$V_{EB} = 4.0V, I_{C} = 0$		50	nA
On Charact	eristics		•	•	
h <sub>FE</sub>	DC Current Gain	$I_{C} = 1.0$ mA, $V_{CE} = 5.0$ V $I_{C} = 10$ mA, $V_{CE} = 5.0$ V $I_{C} = 50$ mA, $V_{CE} = 5.0$ V	60 60 20	250	
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA I <sub>C</sub> = 50mA, I <sub>B</sub> = 5.0mA		0.15 0.25	V V
V <sub>BE(sat)</sub>	Base-Emitter On Voltage	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA I <sub>C</sub> = 50mA, I <sub>B</sub> = 5.0mA		1.0 1.2	V V

<sup>1.</sup> These ratings are based on a maximum junction temperature of 150 degrees  $\ensuremath{\text{C}}$ .

<sup>2.</sup> These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

## **Electrical Characteristics** $T_a = 25$ °C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units	
Small Signa	Small Signal Characteristics					
f <sub>T</sub>	Current Gain Bandwidth Product	I <sub>C</sub> = 10mA, V <sub>CE</sub> = 10V, f = 100MHz	50		MHz	
C <sub>obo</sub>	Output Capacitance	V <sub>CB</sub> = 10V, I <sub>E</sub> = 0, f = 1.0MHz		6.0	pF	
C <sub>ibo</sub>	Input Capacitance	$V_{BE} = 0.5V, I_{C} = 0, f = 1.0MHz$		30	pF	

## Thermal Characteristics T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Max.	Units
$P_{D}$	Total Device Dissipation Derate above 25°C	350 2.8	mW mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

<sup>\*</sup> Device mounted on FR-4 PCB 1.6" × 1.6" × 0.06."

## **Package Marking and Ordering Information**

<b>Device Marking</b>	Device	Package	Reel Size	Tape Width	Quantity
1F	MMBT5550	SOT-23	7"		3,000

### **Typical Performance Characteristics**

Figure 1. Typical Pulsed Current Gain vs Collector Current

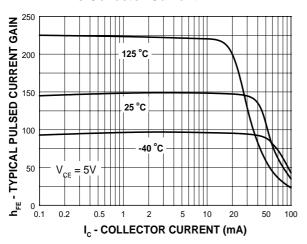


Figure 3. Base-Emitter Saturation Voltage vs Collector Current

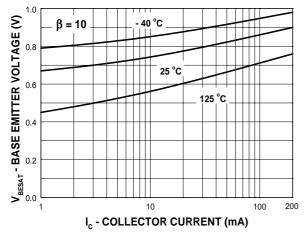


Figure 5. Collector Cutoff Current vs Ambient Temperature

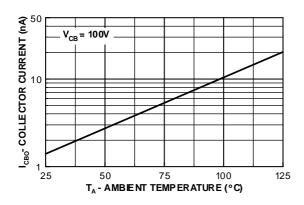


Figure 2. Collector-Emitter Saturation Voltage vs Collector Current

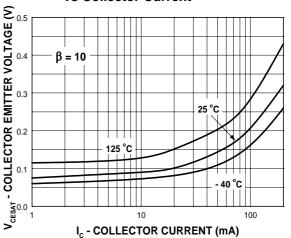


Figure 4. Base-Emitter On Voltage vs Collector Current

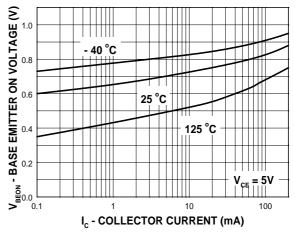
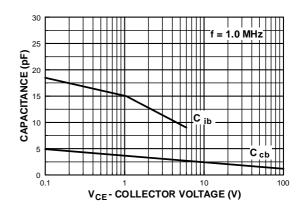
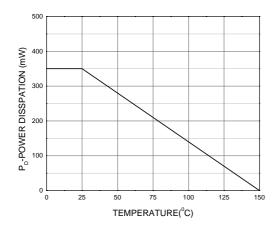


Figure 6. Input and Output Capacitance vs Reverse Voltaget



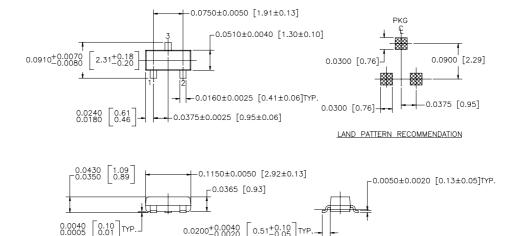
## Typical Performance Characteristics (Continued)

Figure 7. Power Dissipation vs Ambient Temperature



### **Mechanical Dimensions**

## SOT-23



SOT 23, 3 LEADS LOW PROFILE

NOTE: UNLESS OTHERWISE SPECIFIED

- 1. STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42
- 2. REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE G, DATED JUL 1993

Dimensions in Millimeters

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### **Definition of Terms**

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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